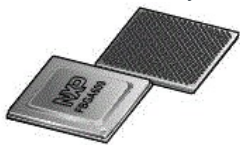




SIMX8DX5AVLF1BB(Active)

Package  **FBGA609** FBGA609, fine-pitch ball grid array package; 609 terminals, 0.8 mm pitch, 21 mm x 21 mm x 2.37 mm body



[Buy Options](#) | [Operating Characteristics](#) | [Environmental Information](#) | [Quality Information](#) | [Shipping Information](#)

Buy Options

SIMX8DX5AVLF1BB
935389375557
Active
TRAY-Tray, Bakeable, Multiple in Drypack

Min. Package Quantity: 60
Lead Time: 20 weeks

>
Available Distributors: SIMX8DX5AVLF1BB

 [SIMX8DX5AVLF1BBR](#)
935389375518
Active
REEL-Reel 13" Q1/T1 in Drypack

Min. Package Quantity: 500
Lead Time: 20 weeks

Operating Characteristics

No information available

Environmental Information

Material Declaration	Pb-Free	EU RoHS	Halogen Free	RHF Indicator	REACH SVHC	Weight (mg)
SIMX8DX5AVLF1BB(935389375557)	Yes	Yes	Yes	D	REACH SVHC	3081.5
SIMX8DX5AVLF1BBR (935389375518)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	REACH SVHC	3081.5

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
SIMX8DX5AVLF1BB (935389375557)	No	3	260	40
SIMX8DX5AVLF1BBR (935389375518)	No	3	260	40

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)
SIMX8DX5AVLF1BB (935389375557)	854231	5A992C
SIMX8DX5AVLF1BBR (935389375518)	854231	5A992C

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